

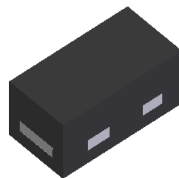
Features

- Ultra-Small, Low Profile Leadless Surface Mount Package (0.6 x 0.3 x 0.3mm)
- Provides ESD Protection per IEC 61000-4-2 Standard: Air – ±30kV, Contact – ±25kV
- 1 Channel of ESD Protection
- Low Channel Input Capacitance
- Typically Used in Cellular Handsets, Portable Electronics, Communication Systems, Computers and Peripherals
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

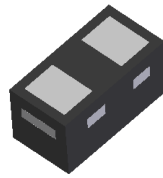
Mechanical Data

- Case: X3-DFN0603-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin over Copper Leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.0002 grams (Approximate)

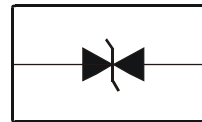
X3-DFN0603-2



Top View



Bottom View



Device Schematic

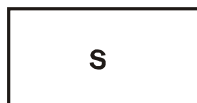
Ordering Information (Note 4)

Product	Compliance	Marking	Reel size(inches)	Tape width(mm)	Quantity per reel
DESD3V3S1BLP3-7	Standard	S	7	8	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information

X3-DFN0603-2



S = Product Type Marking Code

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P _{PP}	35	W	8/20μs, Per Fig. 3
Peak Pulse Current	I _{PP}	5	A	8/20μs, Per Fig. 3
ESD Protection – Contact Discharge	V _{ESD_Contact}	±25	kV	IEC 61000-4-2 Standard
ESD Protection – Air Discharge	V _{ESD_Air}	±30	kV	IEC 61000-4-2 Standard

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P_D	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	500	$^{\circ}\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^{\circ}\text{C}$

Electrical Characteristics (@ $T_A = +25^{\circ}\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	V_{RWM}	—	—	3.3	V	—
Channel Leakage Current (Note 6)	I_{RM}	—	10	100	nA	$V_{RWM} = 3.3\text{V}$
Clamping Voltage, Positive Transients	V_{CL}	—	4.5 5.8	5.4 7.0	V	$I_{PP} = 1\text{A}, t_p = 8/20\mu\text{S}$ $I_{PP} = 5\text{A}, t_p = 8/20\mu\text{S}$
Breakdown Voltage	V_{BR}	3.8	—	6.5	V	$I_R = 1\text{mA}$
Differential Resistance	R_{DIF}	—	0.3	—	Ω	$I_R = 1\text{A}$
Channel Input Capacitance	C_T	—	10	13	pF	$V_R = 0\text{V}, f = 1\text{MHz}$

Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.

6. Short duration pulse test used to minimize self-heating effect.

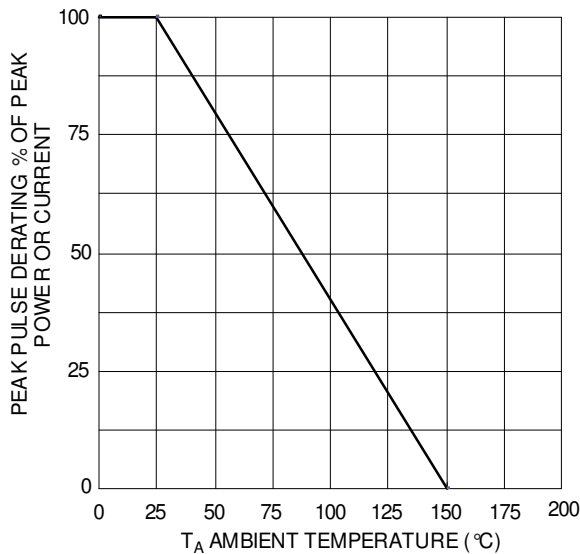


Figure 1 Pulse Derating Curve

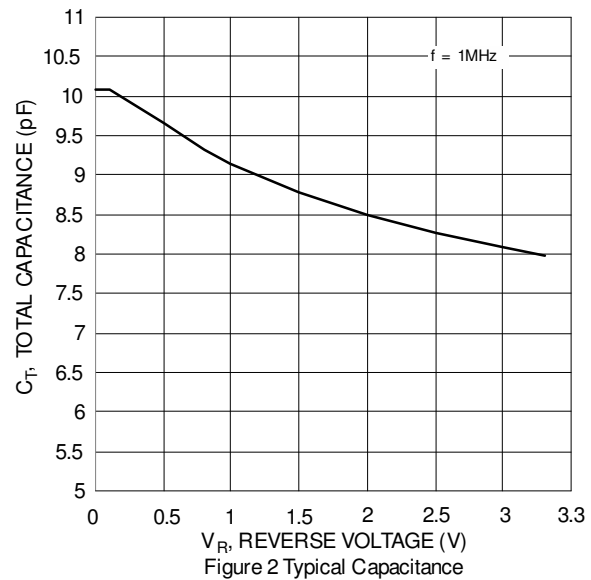


Figure 2 Typical Capacitance

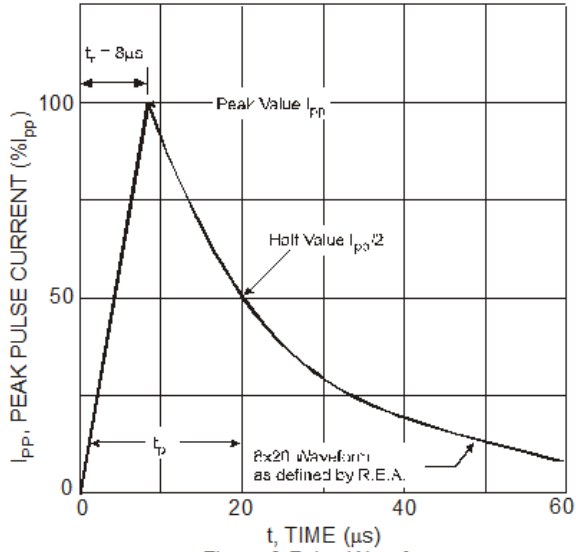


Figure 3 Pulse Waveform

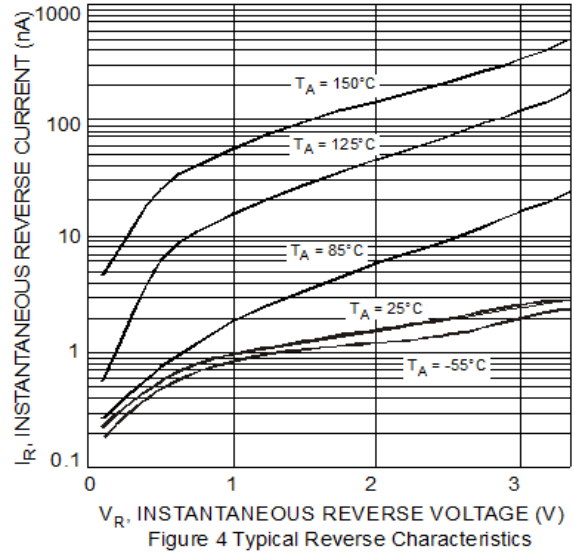


Figure 4 Typical Reverse Characteristics

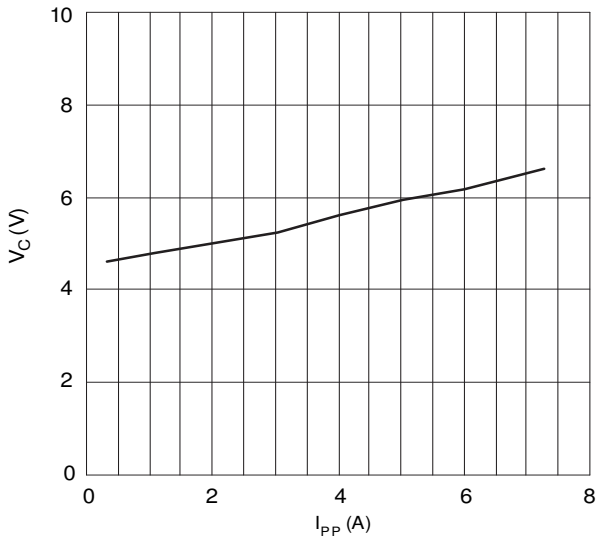


Figure 5 Typical Peak Clamping Voltage V_C vs. Peak Pulse Current I_{PP}

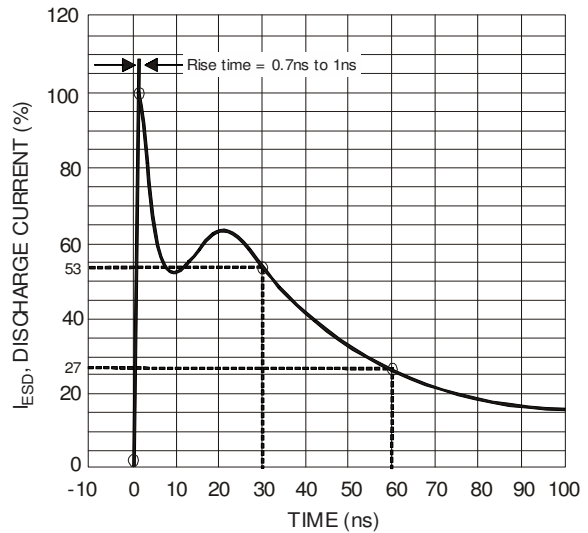


Figure 6 ESD Discharge Current Wave Form IEC 6100-4-2 (330 Ω /150pF)

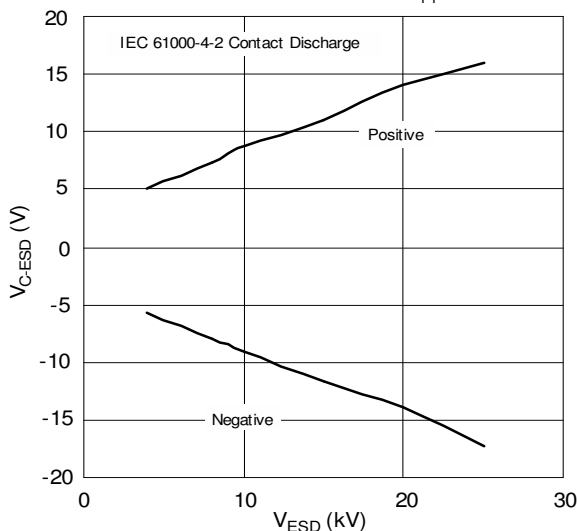


Figure 7 Typical Clamping Voltage vs. Contact Discharge Voltage

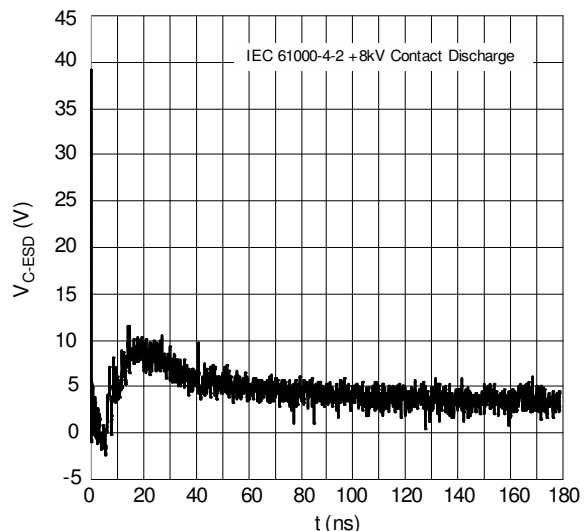


Figure 8 Typical Clamping Performance @ 8kV Contact Discharge

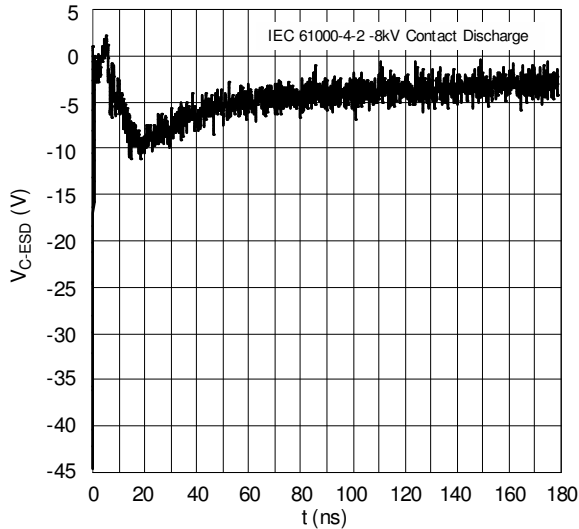
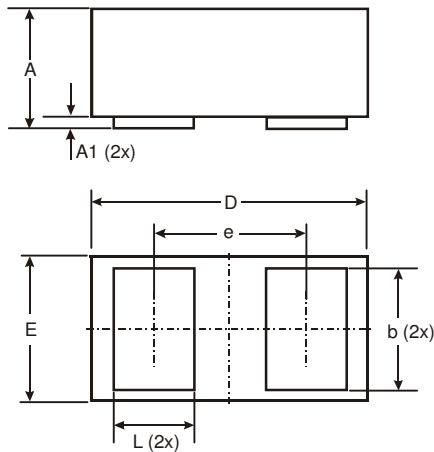


Figure 9 Typical Clamping Performance
@ -8kV Contact Discharge

Package Outline Dimensions

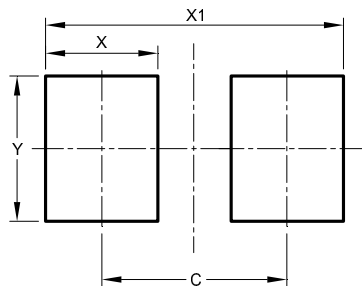
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



X3-DFN0603-2			
Dim	Min	Max	Typ
A	0.27	0.35	0.30
A1	0.00	0.03	0.02
b	0.19	0.29	0.24
D	0.595	0.645	0.62
E	0.295	0.345	0.32
e	-	-	0.355
L	0.14	0.24	0.19
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.380
X	0.230
X1	0.610
Y	0.300

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